



Amendments to the Claims

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (*Currently amended*) An integrated circuit, comprising:
 a fuse corner pad located at a [[first]] corner of the integrated circuit, said fuse corner pad having first and second edges that define said corner of said integrated circuit,
 wherein said fuse corner pad includes a fuse contact ~~coupled to~~ integrated with said fuse corner pad, ~~and~~
 ~~wherein said fuse corner pad is incapable of being bonded to an external electrical connection.~~
2. (*Original*) The integrated circuit of claim 1, further comprising:
 a fuse element connected to said fuse contact.
3. (*Original*) The integrated circuit of claim 2, wherein said fuse element is adapted to adjust a transmitting waveform to comply with a predefined parameter.
4. (*Original*) The integrated circuit of claim 2, wherein said fuse element is adapted to communicate a state of said fuse element, said state identifying the integrated circuit.
5. (*Original*) The integrated circuit of claim 1, wherein said fuse contact is capable of being probed without being bonded to an external connection.
6. (*Original*) The integrated circuit of claim 1, further comprising:
 an auxiliary pad coupled to said fuse corner pad.
7. (*Original*) The integrated circuit of claim 6, wherein said auxiliary pad is a second fuse contact.

8. (*Original*) The integrated circuit of claim 6, wherein said auxiliary pad communicates signals for circuit testing.

9. (*Canceled*)

10. (*Canceled*)

11. (*Currently amended*) A semiconductor die, comprising:
at least one I/O pad, on the semiconductor die, for communicating signals;
and

a fuse corner pad having a fuse integrated within said fuse corner pad, wherein said fuse corner pad is ~~located at a corner of the semiconductor die, includes first and second edges that define a corner of the semiconductor die and wherein said fuse corner pad is incapable of being bonded to an external electrical connection.~~

12. (*Original*) The semiconductor die of claim 11, wherein said fuse corner pad is capable of being probed without being bonded to an external connection.

13. (*Original*) The semiconductor die of claim 11, wherein said fuse corner pad is one of four fuse corner pads, wherein each of said four fuse corner pads is located at a respective corner of the semiconductor die.

14. (*Currently amended*) An integrated circuit, comprising:
a fuse corner pad located at a [[first]] corner of the integrated circuit, said fuse corner pad having first and second edges that define said corner of the integrated circuit,

wherein said fuse corner pad includes a plurality of fuse contacts coupled to said fuse corner pad, ~~and wherein said fuse corner pad is incapable of being bonded to an external electrical connection.~~

15. (*Original*) The integrated circuit of claim 14, wherein at least one of said plurality of fuse contacts is connected to a fuse element included in the integrated circuit.